

# MECHANICAL CASE OUTLINE

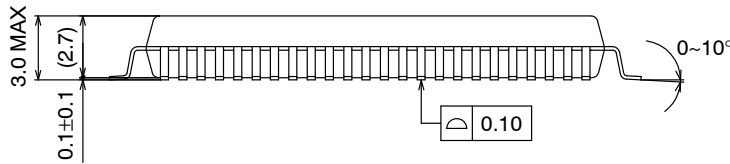
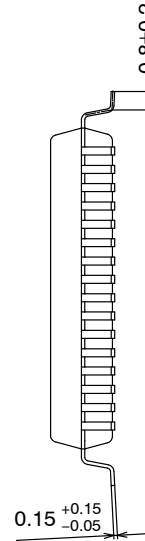
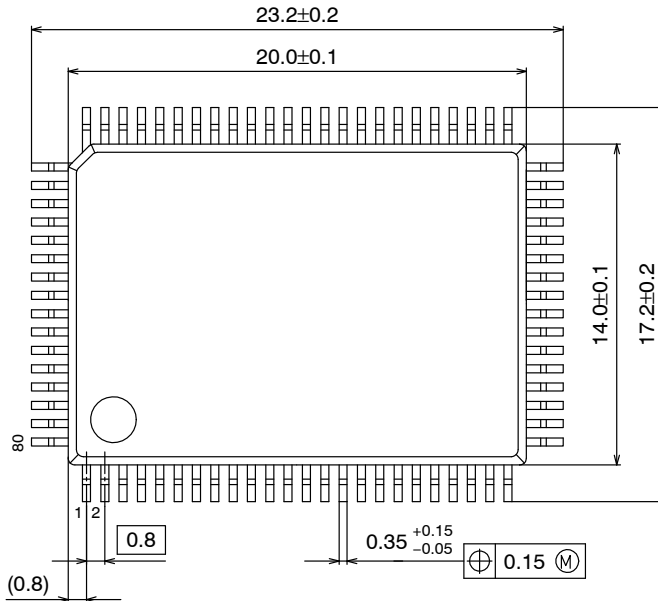
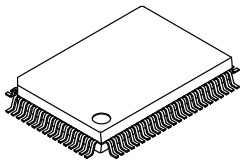
## PACKAGE DIMENSIONS

ON Semiconductor®

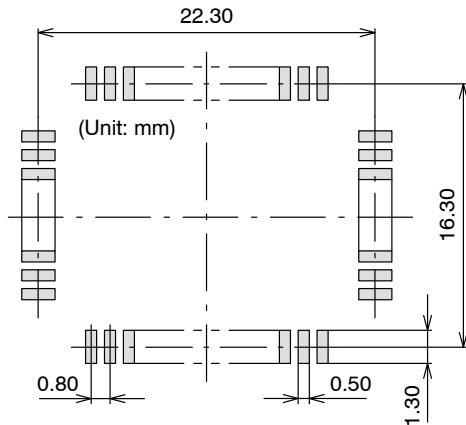


### PQFP80 14x20 / QIP80E CASE 122BS ISSUE A

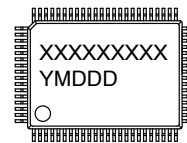
DATE 07 NOV 2013



#### SOLDERING FOOTPRINT\*



#### GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code  
Y = Year  
M = Month  
DDD = Additional Traceability Data

NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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|-------------------------|----------------------------------|--|
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| <b>STATUS:</b>          | <b>ON SEMICONDUCTOR STANDARD</b> |  |
| <b>NEW STANDARD:</b>    |                                  |  |
| <b>DESCRIPTION:</b>     | <b>PQFP80 / QIP80E 14X20</b>     | <b>PAGE 1 OF 2</b>   |

